

**CICMT 2009 Tabletop Exhibit Application**

IMAPS ID # \_\_\_\_\_ ACerS ID# \_\_\_\_\_

Company \_\_\_\_\_

Contact \_\_\_\_\_

Address \_\_\_\_\_

City/State \_\_\_\_\_

Zip \_\_\_\_\_ Country \_\_\_\_\_

Phone \_\_\_\_\_ Fax \_\_\_\_\_

E-mail \_\_\_\_\_

Webpage \_\_\_\_\_

**Cost:** Thru 3/20/09 After 3/20/09

IMAPS/ACerS Member\* \$550 \$650

Non-Member \$700 \$800

\*Corporate Member

Yes, our company will purchase one tabletop space.

Yes, our company will participate in the CD-ROM\*.  
**(free-of-charge)** \*Submit electronic file (Word or PDF) to abell@imaps.org not later than March 20, 2009.

Our check is enclosed for the full rental amount of \$\_\_\_\_\_ payable to IMAPS in US funds.

Please charge my credit card the full amount of \_\_\_\_\_.

AMEX  VISA  MC  Diners  Discover

Card # \_\_\_\_\_

Exp Date: \_\_\_\_\_

Card Holder's Name \_\_\_\_\_

Signature \_\_\_\_\_

Card Billing Address (if different than above)

**Cancellation Policy:** Booth cancellations made before 3/20/09 will receive a refund minus \$100 handling fee. Booths cancelled after 3/20/09 will not be refunded.

*Sponsored by:*



**IMAPS -  
International Microelectronics  
And Packaging Society**

and

**ACerS -  
The American Ceramic Society**



**IMAPS  
611 2nd Street, N.E.  
Washington, D.C. 20002  
Ph: 202-548-4001  
Fax: 202-548-6115  
imaps@imaps.org  
www.imaps.org**

*Everything in electronics between  
the chip and the system!*

Reserve your booth online at  
**www.cicmt.org**  
or complete this form and  
fax it back to  
**202-548-6115.**

**CICMT 2009**

**International Conference  
on  
Ceramic Interconnect  
and  
Ceramic Microsystems  
Technologies**

**Tabletop  
Exhibit  
Application**

**Exhibition  
April 21 & 22, 2009**

**The Curtis Hotel  
Denver, Colorado - USA**

**Conference  
April 20 - 23, 2009**



**www.cicmt.org**

# CICMT 2009

The International Microelectronics and Packaging Society (IMAPS) and the American Ceramic Society (ACerS) are again cooperating in the production of the IMAPS/ACerS Fifth International Conference on Ceramic Interconnect and Ceramic Microsystems Technologies (CICMT 2009).

CICMT 2009 will bring together a diverse set of disciplines to share experiences and promote opportunities to accelerate research, development and application of ceramic interconnect and ceramic microsystems technologies.

The Ceramic Interconnect track focuses on cost effective and reliable high performance ceramic interconnect products for hostile thermal and chemical environments in the automotive, aerospace, defense/security, and communication industries.

The Ceramic Microsystems track focuses on emerging applications and new products that exploit the ability of 3-D ceramic structures to integrate interconnect/packaging with microfluidic, optical, micro-reactor and sensing functions. Tape casting, thick film hybrid, direct write and rapid prototyping technologies are common to both tracks, with emphasis on material, processes, prototype development, advanced design and application opportunities.

## Special Features

- Invited keynote and international presentations
- An exhibition for suppliers who support the use of the technologies.
- A technical poster session to promote student participation.

[www.cicmt.org](http://www.cicmt.org)

## EXHIBITION INFORMATION

### Exhibit Hours: 2 Full Days

**Tuesday, April 21 12:00 noon - 7:30 pm**  
*Lunch, Refreshment Breaks & a Reception will be held in the Exhibit Area.*

**Wednesday, April 22 10:00 am - 4:00 pm**  
*Lunch and Refreshment Breaks will be held in the Exhibit Area.*

#### Installation Hours:

Tuesday, April 21 7:00 am - 11:00 am

#### Dismantle Hours:

Wednesday, April 22 3:00 pm - 8:00 pm

#### Tabletop Registration Fees:\*

	Thru 3/20/09	After 3/20/09
*IMAPS/ACerS Member	\$550	\$650
Non-Member	\$700	\$800
*Corporate Members		

#### Included with your registration:

- one (1) six foot draped table
  - two (2) chairs
  - carpeting
  - one (1) Technical Proceedings CD-ROM
  - one (1) List of Attendees\*
  - two (2) Booth Personnel
- \*Sent after the event.*

Additional booth personnel are welcome at an extra cost of \$50 per person. Registrations for the full conference are not included, but are available at an additional cost.

Shipments are made to the Hotel directly. You save money because no service contractor is involved!

**The Curtis Hotel**  
**1405 Curtis Street**  
**Denver, CO 80202**  
**(800) 525 6651**

## Marketing Feature Available for Exhibitors

IMAPS offers all exhibitors the option of providing an unlimited amount of pages of company products, services and contact information to be included in the Technical Proceedings CD-ROM. These CD-ROMs are provided to all technical conference attendees and are for sale through IMAPS to all industry professionals.

This new and unique feature will promote an unlimited amount of promotional material for the Exhibitor's products and abilities much longer than just the Conference. **There is no charge for this optional feature, but the deadline is firm.**

**Submissions must be sent electronically in one (1) file, either PDF or Word, that is easy to open, not password-protected and in a logical format. Any materials not sent in the required format or that arrive after the deadline, may not appear on the CD-ROM. Send files to [bschieman@imaps.org](mailto:bschieman@imaps.org) on or before March 20, 2009.**

### Organizing Committee

#### General Co-Chairs

Michael Lanagan,  
*Penn State University*  
[mlanagan@psu.edu](mailto:mlanagan@psu.edu)

Jun Akedo, *AIST*  
[Akedo-j@aist.go.jp](mailto:Akedo-j@aist.go.jp)

#### Technical Program Co-Chairs

Amy Moll,  
*Boise State University*  
[AMoll@boisestate.edu](mailto:AMoll@boisestate.edu)

Takaaki Tsurumi,  
*Tokyo Institute of Technology*  
[Ttsurumi@ceram.titech.ac.jp](mailto:Ttsurumi@ceram.titech.ac.jp)

Jens Müller,  
*Technical University Ilmenau*  
[jens.mueller@imaps.de](mailto:jens.mueller@imaps.de)

#### Exhibits Contact:

Ann Bell, *IMAPS*  
[abell@imaps.org](mailto:abell@imaps.org) or 202-548-8717